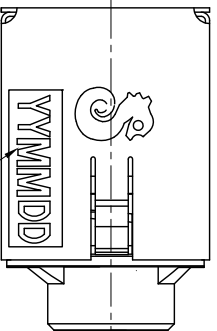
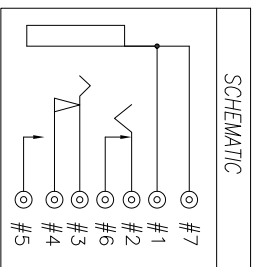
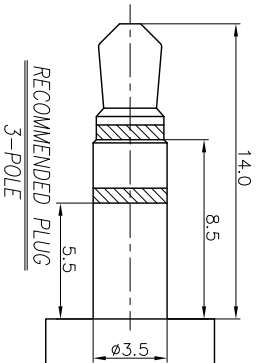


RECOMMENDED PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30m Ω MAX.
 - INSULATION VOLTAGE WITHSTAND:
500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3kg.
 - WITHDRAWAL FORCE: 0.3 - 2kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50m Ω MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50M Ω MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKAGING: TAPE & REEL.
 - TO CONFORM TO SINGAITRON HAZARDOUS SUBSTANCE FREE SPEC
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
 - FOR LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK COLOR
B	EARTH	1	COPPER ALLOY 0.2t	Ag0.5μ m Min, ALL OVER 50μ "N".
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA OVER IN 50μ "
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	120μ " Sn ON SOLDER GOLD FLASH ON CONTACT AREA ALL OVER 50μ " N".
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	N: 1.5μ m MIN.
H	SHIELDING	1		

DECIMALS:	ANGLES:
±0.5	X ±2°
±0.3	X.X ±1°
±0.2	X.XX ±0.1
X.XXX	X.XXX ±0.1

Singaton Enterprise Co., Ltd.
信音企業股份有限公司

3.5ø PHONE JACK

DWN ANDY PART NO. 25T-T351-027
CHKD CERRY SCALE:4:1 UNIT: mm
APVD LAO SIZE: A3 SHEET: 1 OF 1 REV: B

CUSTOMER COPY

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR :T091116-1A	HX	2008.12.8
B	ECN :S140845	ANDY	2014.12.17